L	Hits	Search Text	DB	Time stamp
Number				
2	14563	(wiring near (layer film)) with (hole via)	USPAT; US-PGPUB;	2004/03/31 09:46
			EPO; JPO; DERWENT; IBM TDB	
3	192893	gate and source and drain	USPAT;	2004/03/31
			US-PGPUB; EPO; JPO;	09:46
		,	DERWENT; IBM TDB	
4	2869	' ' ' ' ' - '	USPAT;	2004/03/31
ł		via)) and (gate and source and drain)	US-PGPUB;	09:47
			EPO; JPO;	
			DERWENT; IBM TDB	
5	503477	(insulat\$3 dielectric) near (layer film)	USPAT;	2004/03/31
3	303477	(Insulaces dielectic) hear (Layer IIIm)	US-PGPUB;	09:47
			EPO; JPO;	05.47
			DERWENT;	
			IBM TDB	
6	2643	(((wiring near (layer film)) with (hole	USPAT;	2004/03/31
		via)) and (gate and source and drain))	US-PGPUB;	09:48
		and ((insulat\$3 dielectric) near (layer	EPO; JPO;	
		film))	DERWENT;	
			IBM_TDB	
7	2588	(((()))	USPAT;	2004/03/31
		via)) and (gate and source and drain))	US-PGPUB;	09:49
		and ((insulat\$3 dielectric) near (layer	EPO; JPO;	
		film))) and (substrate wafer)	DERWENT;	l
			IBM TDB	